IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please AMEND claim 29 in accordance with the following:

1-28. (Cancelled)

29. (Currently Amended) An electronic device having mounted thereon a microelectromechanical system (MEMS) element comprising a micromachine component and an electronic component for operation of said micromachine component formed on a substrate of said MEMS element, in which:

a lid having wiring patterns is bonded to the substrate of said MEMS element covering an active surface of said substrate,

an operating space for said micromachine component is defined by said substrate and said lid,

electrodes of said MEMS element and wiring patterns of said lid are electrically connected at a bonded part of said substrate and said lid, and

a sealing portion is provided between said MEMS element and said lid immediately surrounding and adjacent to an outside of said bonded part.

30. (Previously Presented) The electronic device as set forth in claim 29, in which said bonded part is an ultrasonic bonded part of said substrate and said lid.

31. (Previously Presented) The electronic device as set forth in claim 29, in which said substrate and/or said lid further have a cavity at the side of said operating space.

32. (Previously Presented) The electronic device as set forth in claim 29, in which said sealing portion comprises a continuous ultrasonic bonded part formed in contact with an outer periphery of an operating space side of said substrate and said lid without interruption.

33. (Previously Presented) The electronic device as set forth in claim 29, in which said substrate and/or said lid further comprise conductor-filled vias formed passing through said substrate and/or said lid in a thickness direction.

34. (Previously Presented) The electronic device as set forth in claim 29, in which said sealing portion comprises a sealing resin.

35. (Withdrawn) An electronic device having mounted thereon a microelectromechanical system (MEMS) element comprising a micromachine component and an electronic component for operation of said micromachine component formed on a substrate of said MEMS element, in which:

a lid is bonded through an intermediate member having wiring patterns to the substrate of said MEMS element covering an active surface of said substrate,

an operating space for said micromachine component is defined by said substrate, said intermediate member and said lid,

electrodes of said MEMS element and wiring patterns of said intermediate member are electrically connected at a bonded part of said substrate and said intermediate member, and

a sealing portion is provided between said MEMS element and said intermediate member surrounding an outside of said bonded part.

36. (Withdrawn) The electronic device as set forth in claim 35, in which said bonded part is an ultrasonic bonded part of said substrate and said intermediate member.

37. (Withdrawn) The electronic device as set forth in claim 29, in which said intermediate member is provided with an opening for operation of said micromachine component and wiring patterns, and said electronic component and the wiring patterns of said intermediate member are electrically connected.

38. (Withdrawn) The electronic device as set forth in claim 35, in which said sealing portion comprises a continuous ultrasonic bonded part formed in contact with an outer periphery of an operating space side of said substrate and said intermediate member without interruption.

39. (Withdrawn) The electronic device as set forth in claim 35, in which said substrate and/or said intermediate member further comprise conductor-filled vias formed passing through said substrate and/or said intermediate member in a thickness direction.

40. (Withdrawn) The electronic device as set forth in claim 35, in which said sealing portion comprises a sealing resin.

41. (Withdrawn) An electronic device having mounted thereon a microelectromechanical system (MEMS) element comprising a micromachine component and an electronic component for operation of said micromachine component formed on a substrate of said MEMS element, comprising:

a lid having wiring patterns bonded to the substrate of said MEMS element covering an active surface of said substrate;

electrodes of said MEMS element electrically connected at a bonded part of said substrate and said lid directly to said wiring patterns of said lid; and

a sealing portion provided between said MEMS element and said lid, sealing an outer portion of the bonded part of said substrate and said lid,

wherein an operating space for said micromachine component is defined by said substrate and said lid.